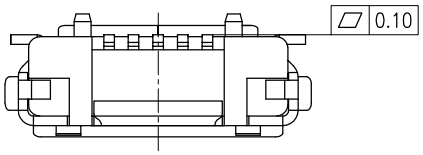
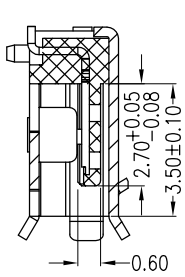
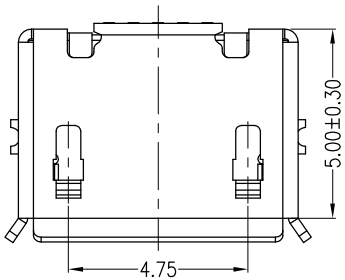
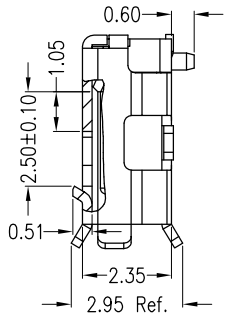
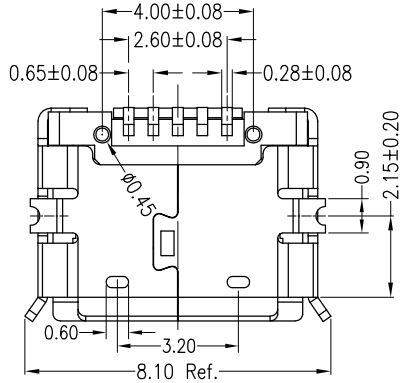
REV.	ECN NO	LOCATIONS	DESCRIPTION	DATE

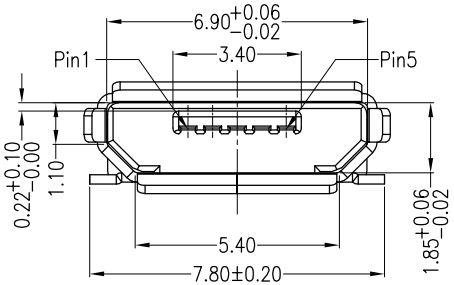


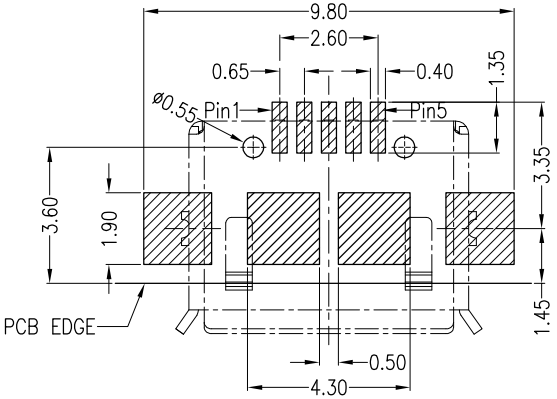












Note:
1.Material:
- 1.1 Housing: High temperature thermoplastic with g.f,UL94v−0
- 1.2 Contact: copper alloy,t=0.20mm
- 1.3 Shell: SUS304,t=0.25mm

2.Specification:
- 2.1 Current rating:1,5PIN 1.8A Max/2,3,4PIN 1A Max.
- 2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.
- 2.3 Contact resistance: 30 mΩ Max.
- 2.4 Insulation resistance: 100 MΩ Min.
- 2.5 Total mating force: 3.57 Kgf Max.
- 2.6 Total unmating force: 1.0 Kgf Min
- 2.7 Temperature range: −30°C~80°C

RECOMMANDED PCB LAYOUT **PCB图仅供参考**

外壳材质
7:SUS304R-1/2H

外壳电镀
1:N50u''
2:雾T50u''
3:N+Au1u''(脚)
4:Au1u''

端子电镀 01:Au1u'';02:Au1.5u'';03:Au3u''
05:Au5u'' ;10:Au10u'';15:Au15u'';30:Au30u''
主体颜色 B:黑色
主体材质 1:LCP
端子材质 4:C5191R-EH

PART NO:		MATERAL:	SEE NOTE
MODEL NO:	XX	FINSH:	SEE NOTE
UNIT: MM	SIZE: A4	COLOR:	SEE NOTE
TOLERANCE UNSPECIFIED		DR:	LIU MIAO
.x 0.15		CHK:	SIMON
.xx 0.10		APP:	DAVID
.xxx 0.05			
Ang. 1°			

WFDCONN 深圳市旺富达电子有限公司 SHEN ZHEN WFD ELECTRONICS CO., LTD

TITLE: **Micro usb** 5s B Type Smt**不锈钢有脚柱**

DWG NO:	REV:
A020	A
SCALE: 5:1	DATE: 2012.05.16